P-Channel Power MOSFET

-20V, -2.8A, 130mΩ

Features

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

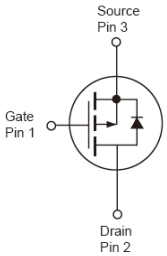
Application

- Telecom power
- Consumer Electronics

KEY PERFORMANCE PARAMETERS			
PARAMETER		**VALUE**	**UNIT**
V_{DS}		-20	V
$R_{DS(on)}$ (max)	V_{GS} = -4.5V	130	mΩ
	V_{GS} = -2.5V	190	
Q_g		7.2	nC

Pb-Free RoHS COMPLIANT HALOGEN FREE

SOT-23



Notes: Moisture sensitivity level: level 3. Per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)				
PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	±12	V
Continuous Drain Current (Note 1)	T_C = 25°C	I_D	-2.8	A
	T_C = 100°C		-1.6	
Pulsed Drain Current (Note 2)		I_{DM}	-10	A
Continuous Source Current (Diode Conduction) (Note 3)		I_S	-1	A
Total Power Dissipation	T_A = 25°C	P_{DTOT}	0.7	W
	T_A = 70°C		0.45	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE			
PARAMETER	**SYMBOL**	**LIMIT**	**UNIT**
Junction to Ambient Thermal Resistance (PCB mounted)	$R_{\Theta JA}$	175	°C/W

Notes: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JA}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. $R_{\Theta JA}$ shown below for single device operation on FR-4 PCB in still air.

ELECTRICAL SPECIFICATIONS (T_C = 25°C unless otherwise noted)						
PARAMETER	**CONDITIONS**	**SYMBOL**	**MIN**	**TYP**	**MAX**	**UNIT**
Static (Note 4)						
Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250µA	BV_{DSS}	-20	--	--	V
Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250µA	$V_{GS(th)}$	-0.6	-0.7	-1	V
Gate Body Leakage	V_{GS} = ±12V, V_{DS} = 0V	I_{GSS}	--	--	±100	nA
Zero Gate Voltage Drain Current	V_{DS} = -20V, V_{GS} = 0V	I_{DSS}	--	--	1.0	µA
Drain-Source On-State Resistance	V_{GS} = -4.5V, I_D = -2.8A	$R_{DS(on)}$	--	90	130	mΩ
	V_{GS} = -2.5V, I_D = -2.0A		--	120	190	
Dynamic (Note 5)						
Gate Resistance	V_{GS} = V_{DS} =0V, f=1MHz	R_g	--	7.5	--	Ω
Total Gate Charge	V_{DS} = -6V, I_D = -2.8A, V_{GS} = -4.5V	Q_g	--	7.2	--	nC
Gate-Source Charge		Q_{gs}	--	2.2	--	
Gate-Drain Charge		Q_{gd}	--	1.2	--	
Input Capacitance	V_{DS} = -15V, V_{GS} = 0V, f = 1.0MHz	C_{iss}	--	480	--	pF
Output Capacitance		C_{oss}	--	460	--	
Reverse Transfer Capacitance		C_{rss}	--	10	--	
Switching (Note 6)						
Turn-On Delay Time	V_{DD} = -6V, R_L = 6Ω, V_{GEN} = -4.5V, R_G = 6Ω	$t_{d(on)}$	--	38	--	ns
Turn-On Rise Time		t_r	--	25	--	
Turn-Off Delay Time		$t_{d(off)}$	--	43	--	
Turn-Off Fall Time		t_f	--	5	--	
Source-Drain Diode (Note 4)						
Forward On Voltage	I_S = -1A, V_{GS} = 0V	V_{SD}	--	-0.7	-1.3	V

Notes:

1. Current limited by package.
2. Pulse width limited by the maximum junction temperature.
3. Surface Mounted on a 1 in^2 pad of 2_{OZ} Cu, t ≤ 10 sec.
4. Pulse test: PW ≤ 300µs, duty cycle ≤ 2%.
5. For DESIGN AID ONLY, not subject to production testing.
6. Switching time is essentially independent of operating temperature.

ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM2301ACX RFG	SOT-23	3,000 pcs / 7” Reel

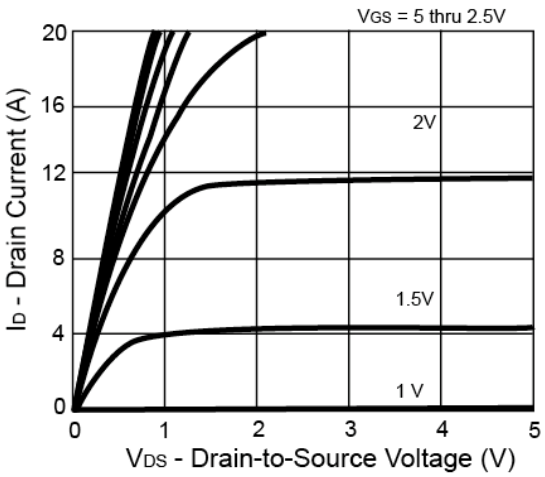
Note:

1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
2. Halogen-free according to IEC 61249-2-21 definition

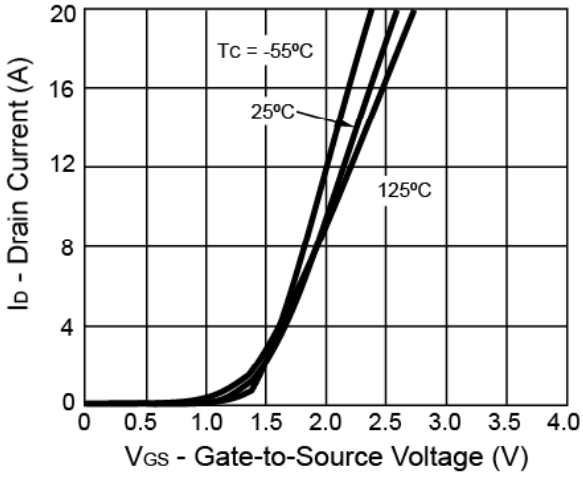
CHARACTERISTICS CURVES

(T_C = 25°C unless otherwise noted)

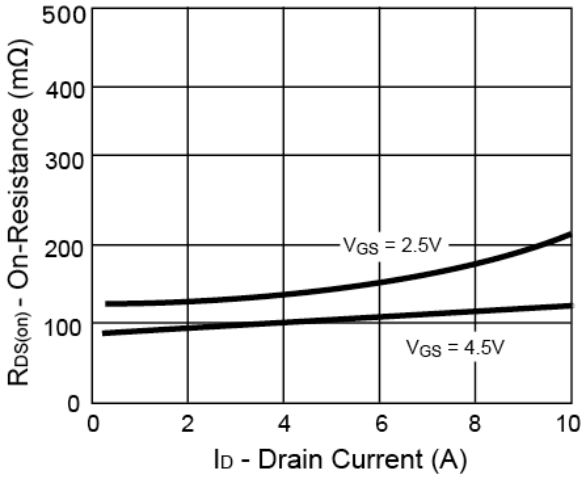
Output Characteristics



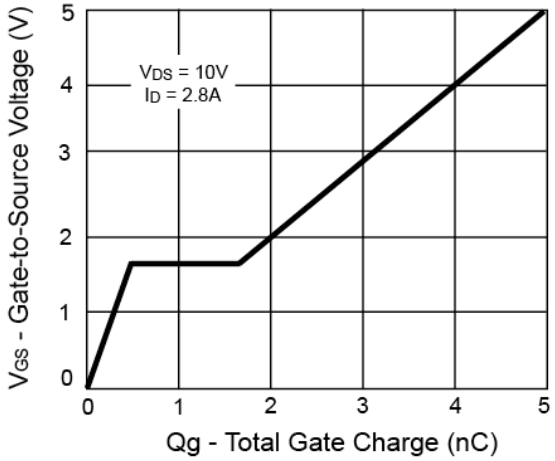
Transfer Characteristics



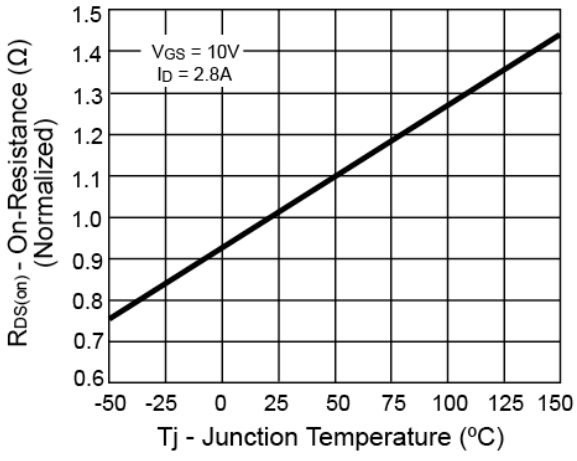
On-Resistance vs. Drain Current



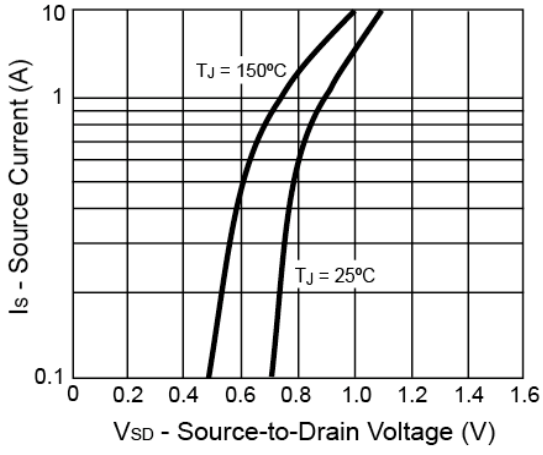
Gate Charge



On-Resistance vs. Junction Temperature



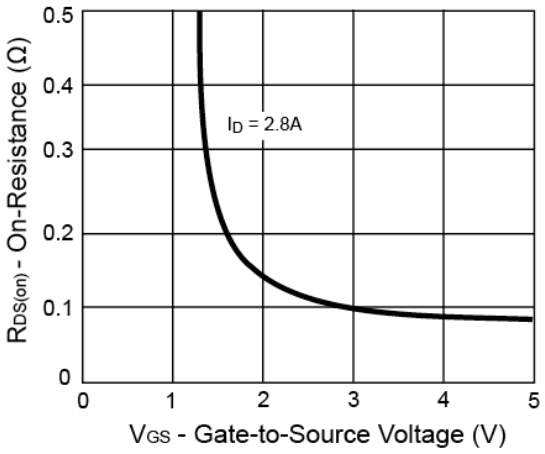
Source-Drain Diode Forward Voltage



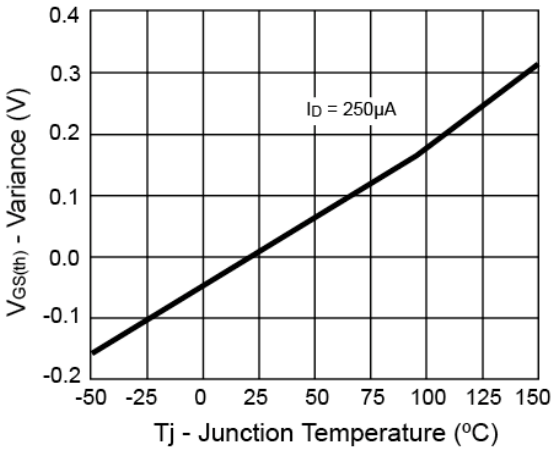
Electrical Characteristics Curve

(Tc= 25°C, unless otherwise noted)

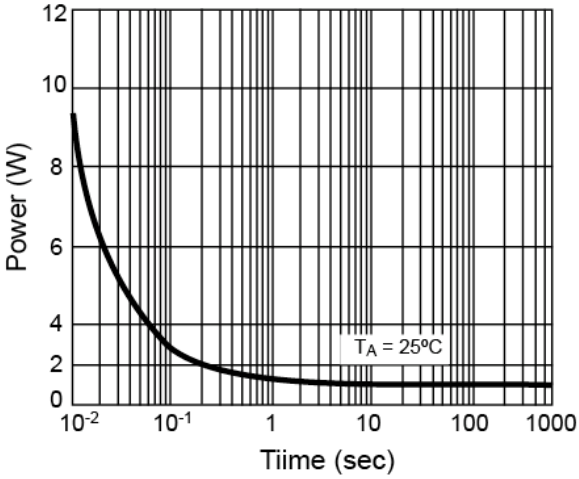
On-Resistance vs. Gate-Source Voltage



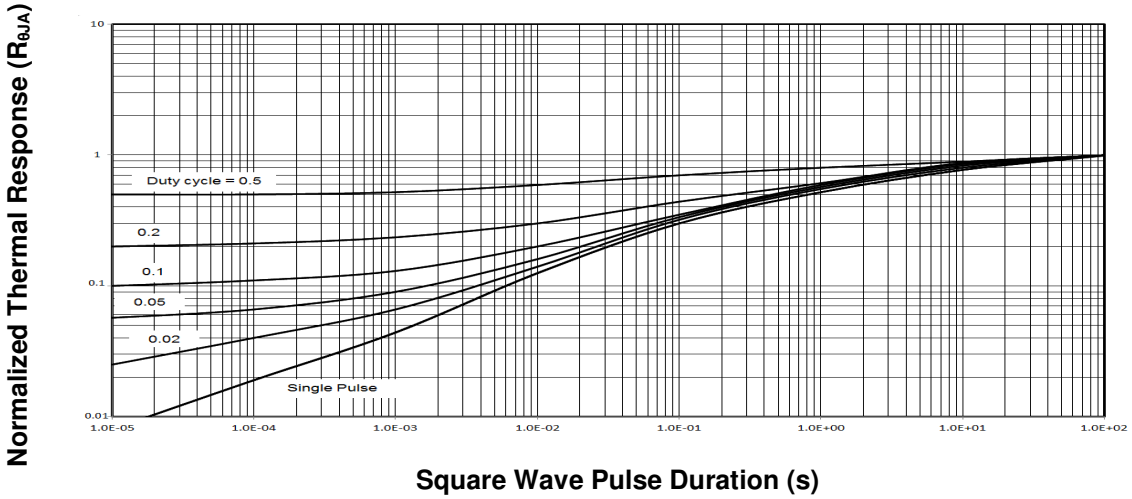
Threshold Voltage



Single Pulse Power

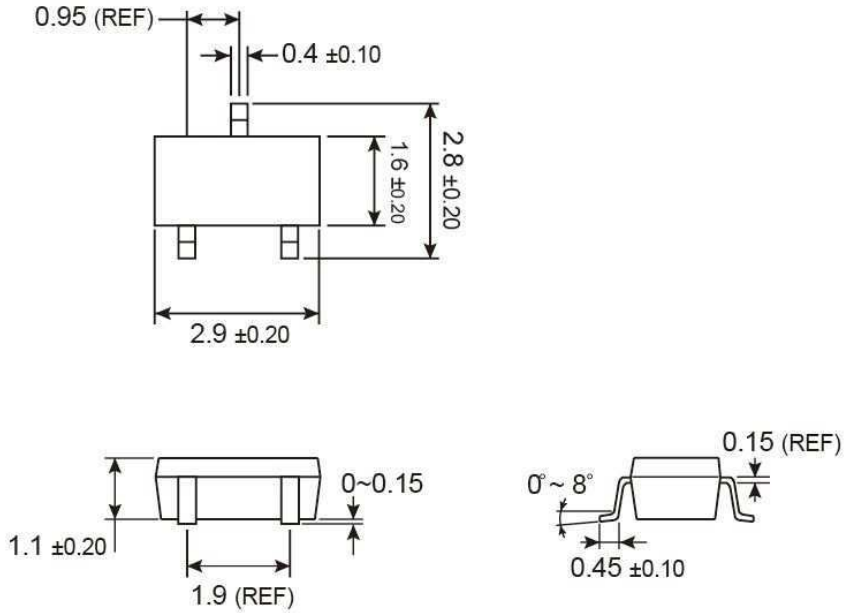


Normalized Thermal Transient Impedance, Junction-to-Ambient

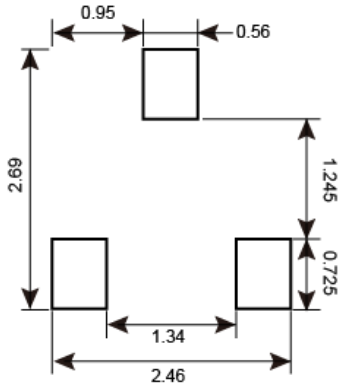


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

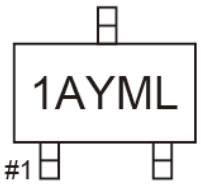
SOT-23



SUGGESTED PAD LAYOUT (Unit: Millimeters)



Marking Diagram



Y = Year Code

M = Month Code for Halogen Free Product

O	=Jan	**P**	=Feb	**Q**	=Mar	**R**	=Apr
S	=May	**T**	=Jun	**U**	=Jul	**V**	=Aug
W	=Sep	**X**	=Oct	**Y**	=Nov	**Z**	=Dec

L = Lot Code

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